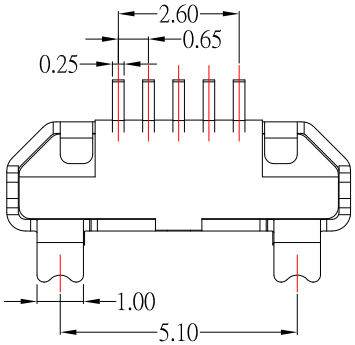
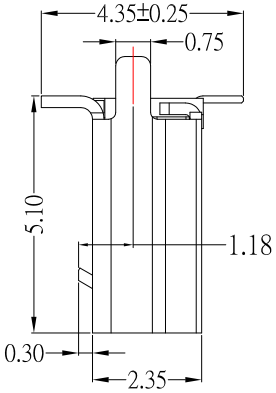
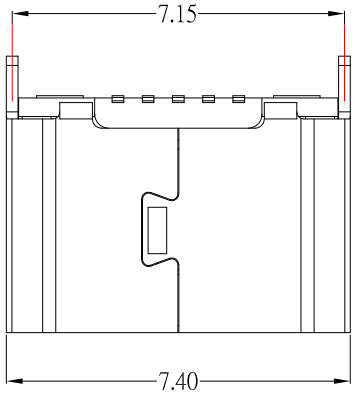
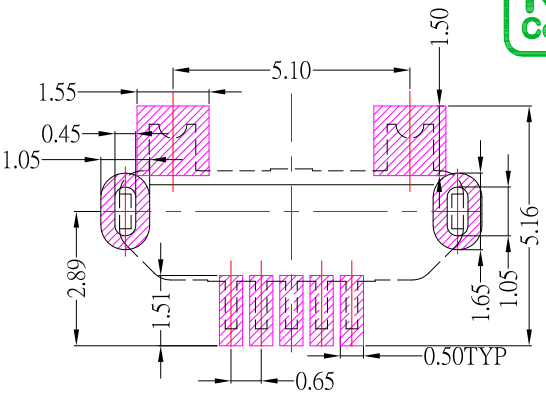
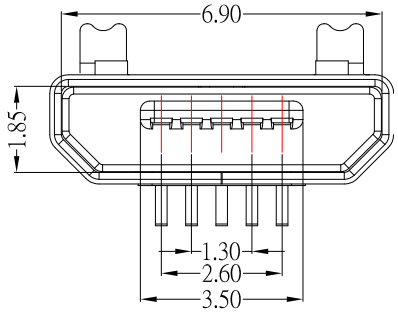








PCB LAYOUT MOUNTING PATTERN



NOTES:t

MATERIAL:

1.1 HOUSING: LCP

1.2 CONTACT: BRASS

1.3 SHELL: SUS

Finish:

2.1 Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls
Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 CURRENT RATING: 1.0A

3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 100 V(ac) FOR 1min

3.3 CONTACT RESISTANCE: 30 mΩ MAX.

3.4 INSULATION RESISTANCE: 100 MΩ MIN.

3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.

3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.

3.7 TEMPERATURE RANGE: -30°C ~ +80°C

ITEM NO.	DESCRIPTION	DRAWN	DATE
8	更新圖面	Jack	030221
7	新增PCB LAYOUT尺寸	Jack	052620
6	更新外殼鍍鎳	Jack	042420
5	更新尺寸	Jack	030220
4	新增PIN編號	Jack	050319
3	更新圖面	Jack	042619
2	新增PCB LAYOUT尺寸	Jack	010319
1	更新為A0版	Jack	041718
10	新增尺寸	Jack	040721
9	新增尺寸	Jack	033121

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CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ± 0.2
Above 5 ~ 15 ± 0.3
Above 15 ~ 30 ± 0.4
Above 30 ~ 50 ± 0.5
Angle ± 0.3°

3RD. ANGEL'S | UNITS | MM

DRAWN BY: Jack Lu	DATE 04/07/21	MAT'L	
CHECKED BY: Jacky Chen	DATE 04/07/21	FINISH	
APPROVED BY: Tony Kao	DATE 04/07/21	SCALE 1 : 1	SHEET NO. 1 of 1

TITLE	CONNECTOR		
MODLE	MICRO USB 5P 直立式SMT ,無捲邊		
DWG NO.	MRUSB-5B-VS7NI-S306	SIZE	A4
PART NO.	MRUSB-5B-VS7NI-S306	VER	R10